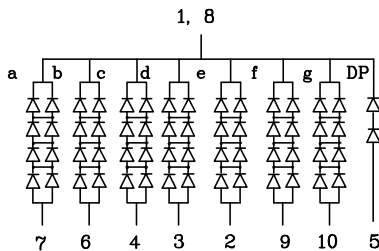


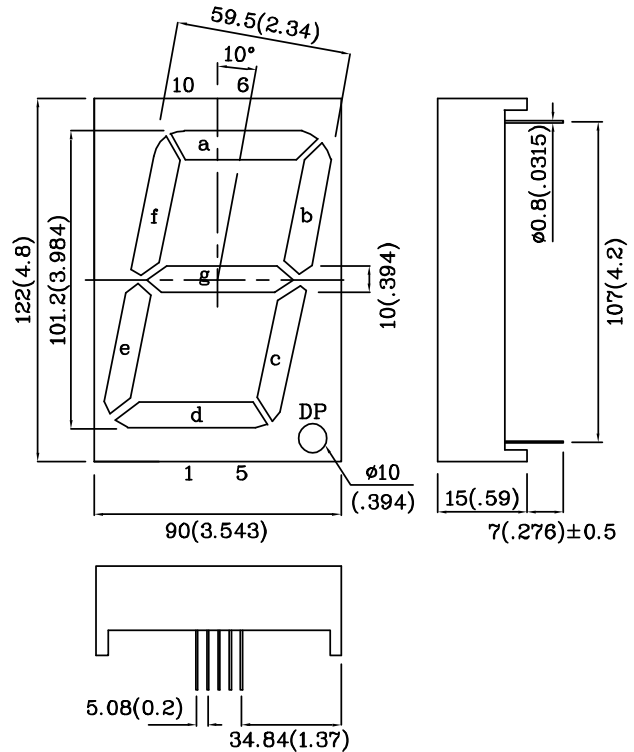
Features

- LARGE SIZE.
- 4.0 INCH DIGIT HEIGHT.
- LOW CURRENT OPERATION.
- EXCELLENT CHARACTER APPEARANCE.
- HIGH LIGHT OUTPUT.
- EASY MOUNTING ON P.C. BOARDS OR SOCKETS.
- I.C. COMPATIBLE.
- MECHANICALLY RUGGED.
- STANDARD : GRAY FACE, WHITE SEGMENT.
- RoHS COMPLIANT.



Notes:

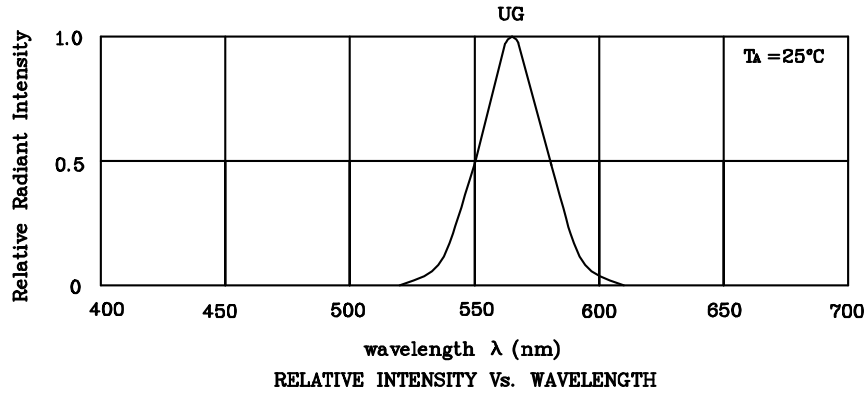
1. All dimensions are in millimeters (inches).
2. Tolerance is $\pm 0.25(0.01")$ unless otherwise noted.



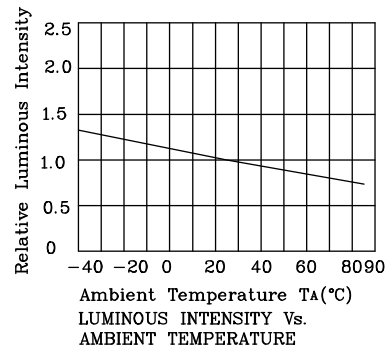
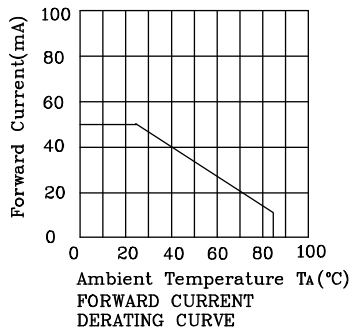
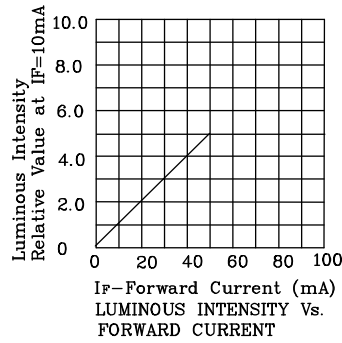
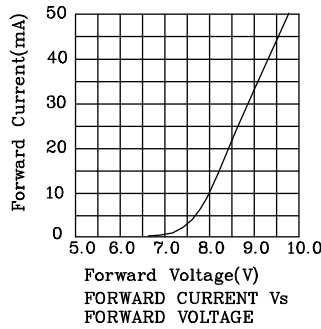
Absolute maximum ratings (TA=25°C)		UG (GaP)	Unit
Reverse Voltage Per Segment or (Dp)	V _R	20 (10)	V
Forward Current Per Segment or (Dp)	I _F	50 (25)	mA
Forward Current (Peak) Per Segment or (Dp) 1/10 Duty Cycle 0.1ms Pulse Width	i _F S	280 (140)	mA
Power Dissipation Per Segment or (Dp)	P _T	500 (125)	mW
Operating Temperature	T _A	-40 ~ +85	°C
Storage Temperature	T _{stg}	-40 ~ +85	
Lead Solder Temperature [2mm Below Package Base]	260°C For 5 Seconds		

Operating Characteristics (TA=25°C)		UG (GaP)	Unit
Forward Voltage (Typ.) Per Segment or (Dp) (I _F =10mA)	V _F	8.0 (4.0)	V
Forward Voltage (Max.) Per Segment or (Dp) (I _F =10mA)	V _F	10.0 (5.0)	V
Reverse Current Per Segment or (Dp) (V _R =20(10)V)	I _R	20 (10)	uA
Wavelength of Peak Emission (I _F =10mA)	λ _P	565	nm
Wavelength of Dominant Emission (I _F =10mA)	λ _D	568	nm
Spectral Line Full Width At Half- Maximum (I _F =10mA)	Δλ	30	nm
Capacitance (V _F =0V, f=1MHz)	C	15	pF

Part Number	Emitting Color	Emitting Material	Luminous Intensity (I _F =10mA) ucd		Wavelength nm λ _P	Description
			min.	typ.		
XDUG100C-A	Green	GaP	12000	59990	565	Common Cathode, Rt. Hand Decimal



❖ **UG**



Remarks:

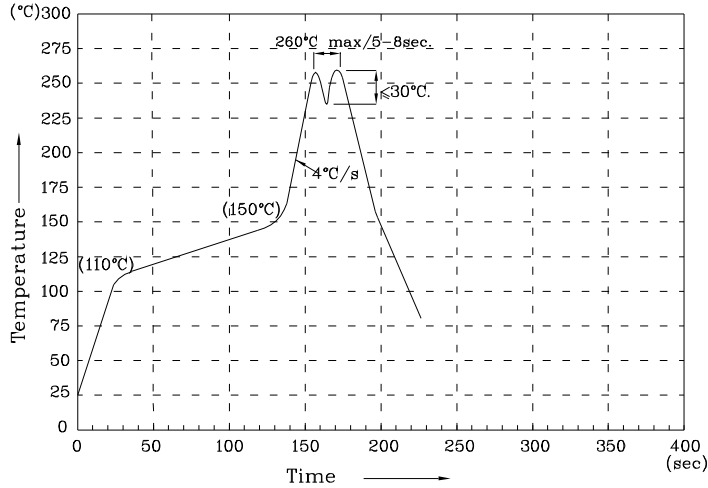
If special sorting is required (e.g. binning based on forward voltage, luminous intensity or wavelength), the typical accuracy of the sorting process is as follows:

1. Wavelength: +/-1nm
2. Luminous Intensity: +/-15%
3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.

XDUG100C-A

Wave Soldering Profile For Lead-free Through-hole LED.



NOTES:

1. Recommend the wave temperature 245°C~260°C. The maximum soldering temperature should be less than 260°C.
2. Do not apply stress on epoxy resins when temperature is over 85 degree°C.
3. The soldering profile apply to the lead free soldering (Sn/Cu/Ag alloy).
4. No more than once.